



Material Content Data Sheet



Sales Product Name		ICE3AR0680VJZ		Issued		19. July 2018		
MA#		MA001147700						
Package		PG-DIP-7-4		Weight*		653.68 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.340	1.28	1.28	12759	12759
leadframe	inorganic material	phosphorus	7723-14-0	0.049	0.01		74	
	non noble metal	zinc	7440-66-6	0.194	0.03		297	
	non noble metal	iron	7439-89-6	3.884	0.59		5942	
wire	non noble metal	copper	7440-50-8	157.726	24.13	24.76	241288	247601
	noble metal	gold	7440-57-5	0.257	0.04	0.04	393	393
	encapsulation	organic material	carbon black	1333-86-4	1.416	0.22		2167
encapsulation	plastics	epoxy resin	-	45.794	7.01		70056	
	inorganic material	silicondioxide	60676-86-0	424.893	64.99	72.22	649998	722221
leadfinish	non noble metal	tin	7440-31-5	6.460	0.99	0.99	9882	9882
plating	noble metal	silver	7440-22-4	1.911	0.29	0.29	2923	2923
glue	plastics	epoxy resin	-	0.414	0.06		633	
	noble metal	silver	7440-22-4	2.346	0.36	0.42	3588	4221
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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